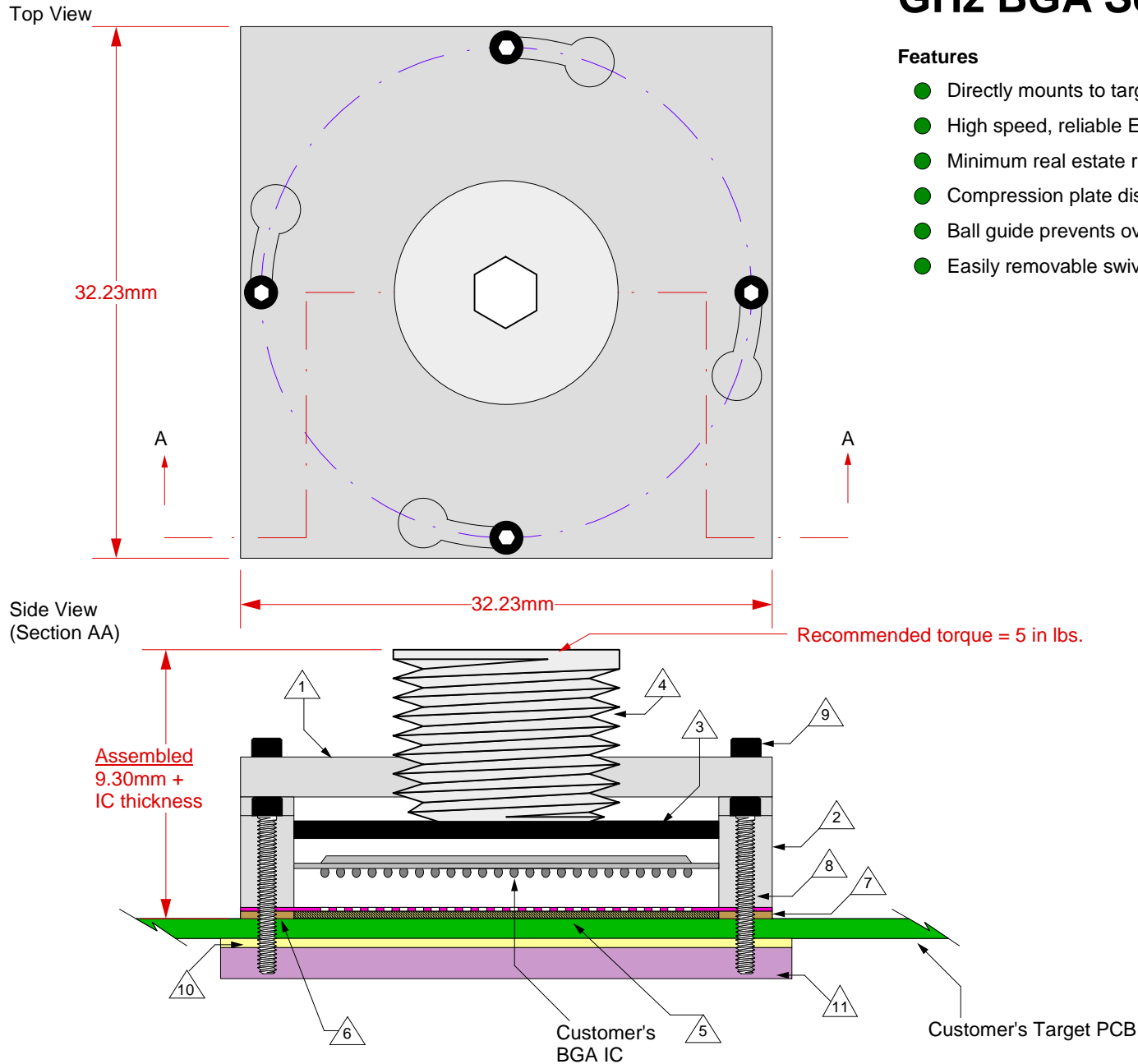


GHz BGA Socket - Direct mount, solderless



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- 1 Socket Lid: Black anodized 6061 Aluminum. Thickness = 2.5mm.
- 2 Socket base: Black anodized 6061 Aluminum. Thickness = 6.5mm.
- 3 Compression Plate: Black anodized 6061 Aluminum. Thickness = 3.5mm.
- 4 Compression screw: Clear anodized 6061 Aluminum. Thickness = 5mm, Hex socket = 5mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- 7 Ball Guide: Kapton polyimide.
- 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 15.87mm long.
- 9 Socket lid screw: Socket head cap, alloy steel with black oxide finish, 4-40 fine thread, 4.76mm long.
- 10 Insulation Plate: FR4/G10, 1.59mm thick.
- 11 Backing Plate: Anodized Aluminum 6.35mm thick.

SG-BGA-6377 Drawing

Status: Released

Scale: -

Rev: A

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Drawing: S. Huang

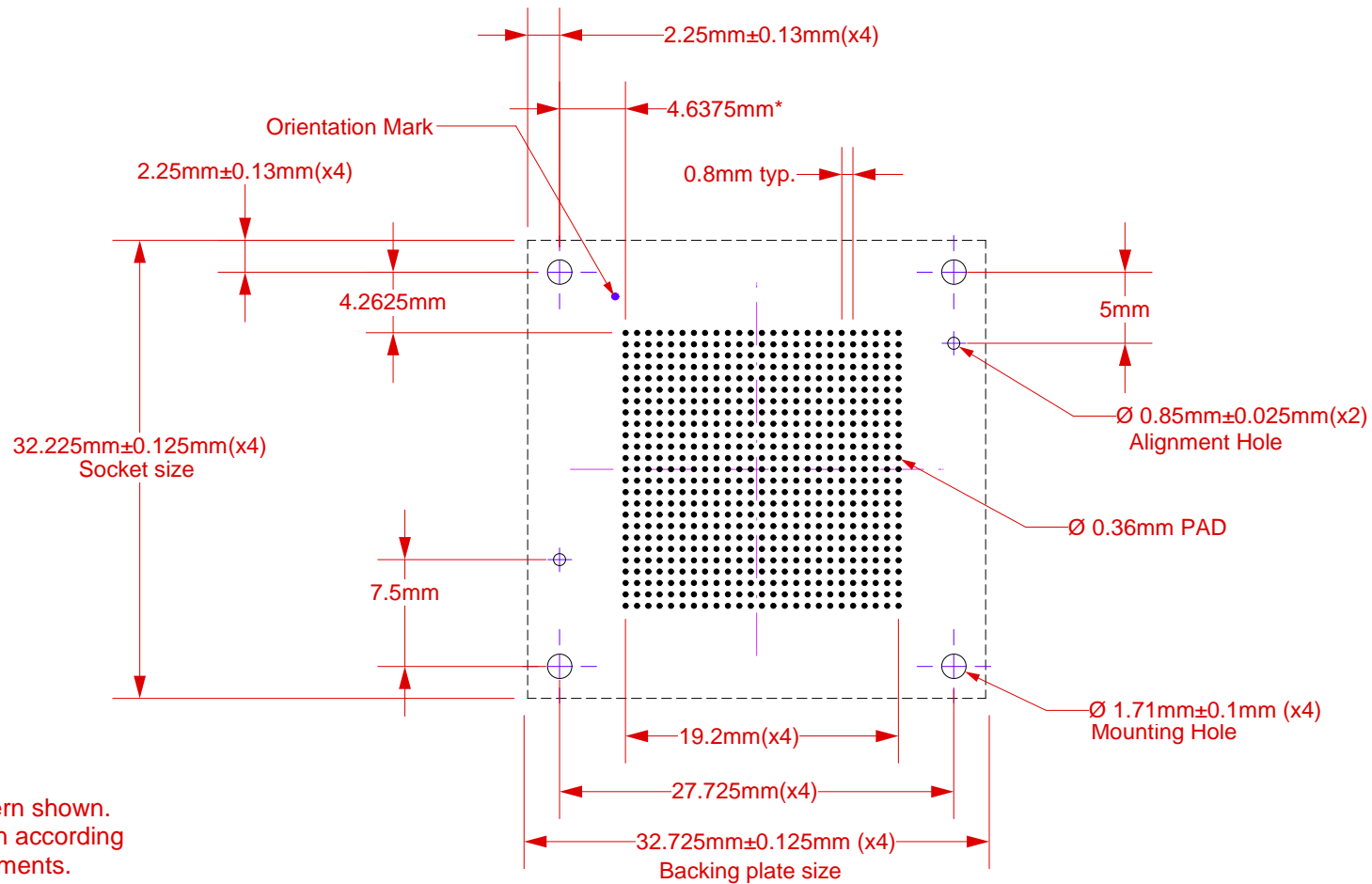
Date: 03/04/2013

File: SG-BGA-6377 Dwg.mcd

Modified:

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes. It is shifted 0.375mm to the center of the right.**




Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

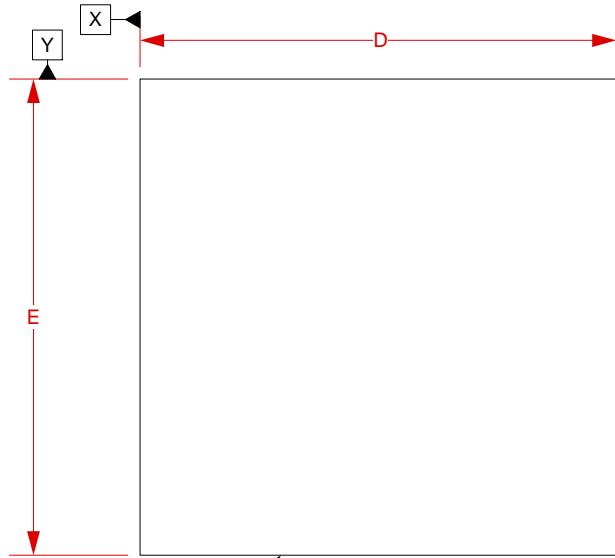
Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

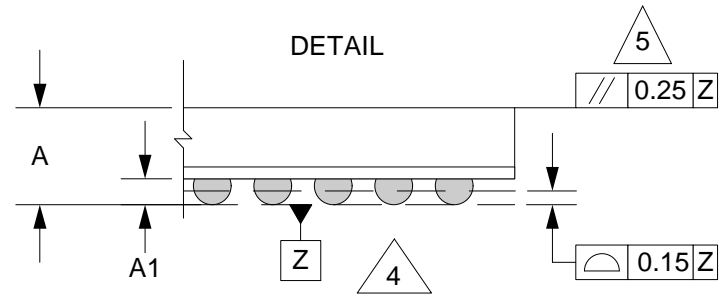
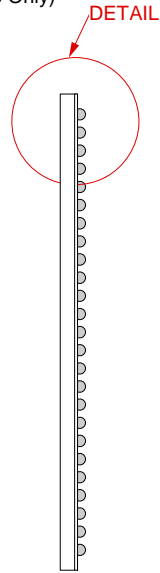
Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

<p>SG-BGA-6377Drawing</p>	<p>Status: Released</p>	<p>Scale: 2:1</p>	<p>Rev: A</p>
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	<p>File: SG-BGA-6377 Dwg.mcd</p>		<p>Modified:</p>

TOP VIEW
(Reference Only)

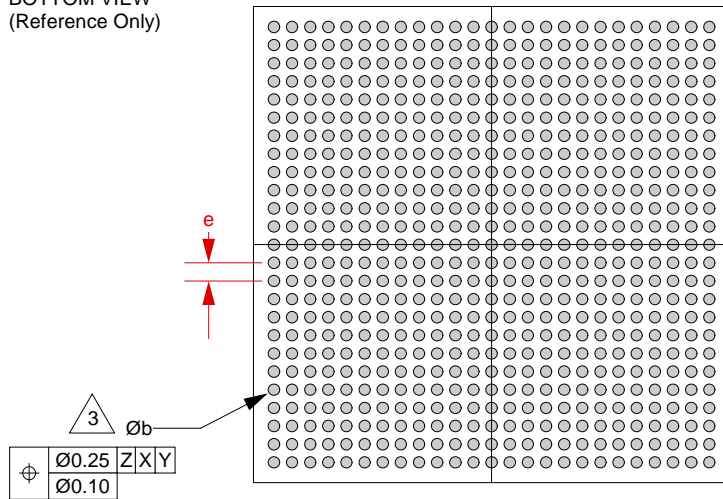


SIDE VIEW
(Reference Only)



Ironwood Package Code: BGA625C1

BOTTOM VIEW
(Reference Only)




DIM	MIN	MAX
A		1.70
A1	0.27	0.45
b		0.55
D	21.00 BSC	
E	21.00 BSC	
e	0.8 BSC	

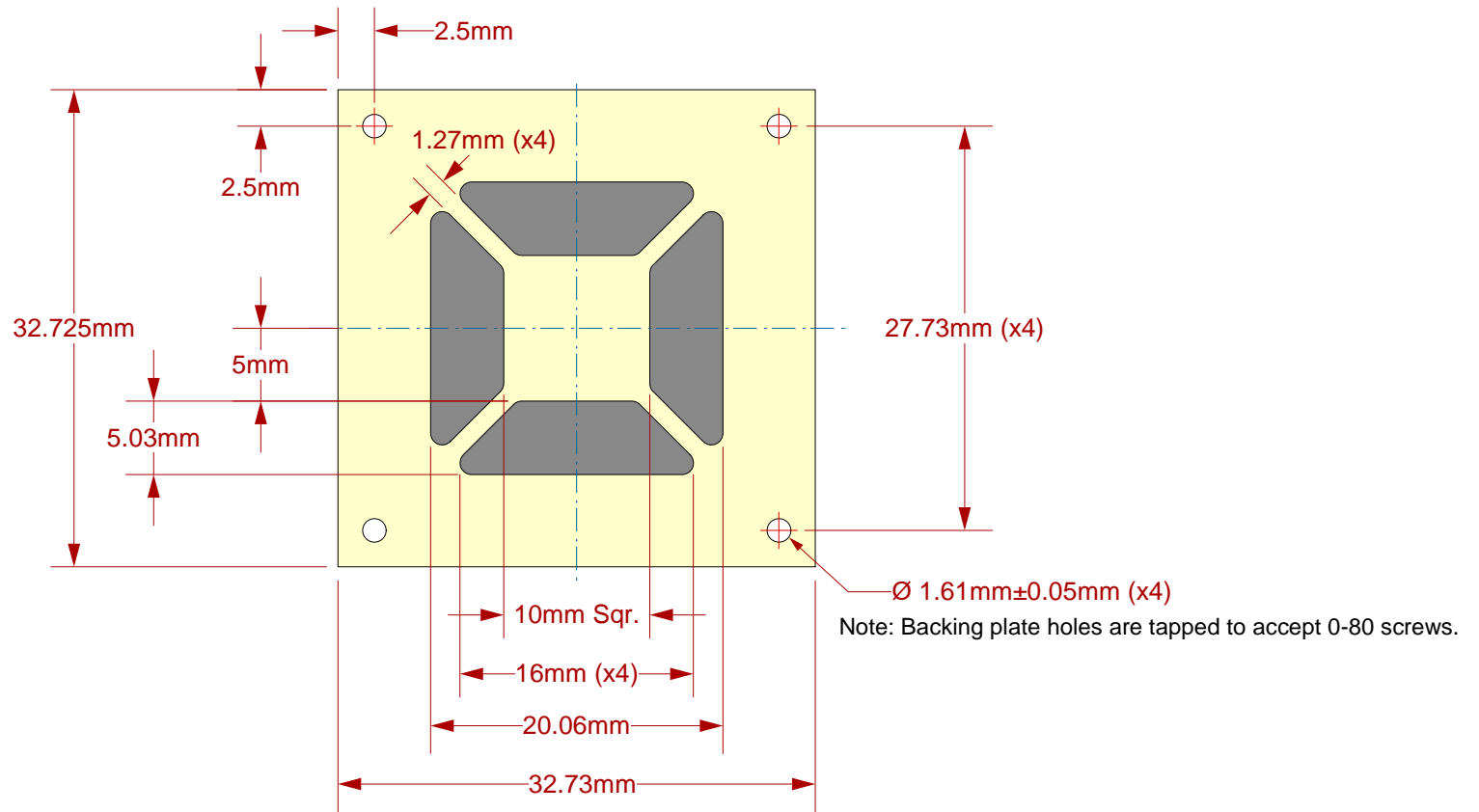
Array 25x25

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.

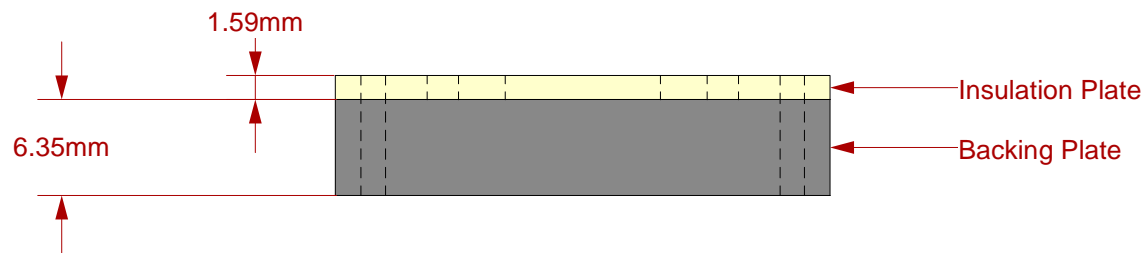
- $\triangle 3$ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z .
- $\triangle 4$ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- $\triangle 5$ Parallelism measurement shall exclude any effect of mark on top surface of package.

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	<p>Drawing: S. Huang</p>	<p>Date: 03/04/2013</p>		
	<p>File: SG-BGA-6377 Dwg.mcd</p>	<p>Modified:</p>		


Top View



Side View



Description: Backing Plate

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	<p>Drawing: S. Huang</p>			<p>Date: 03/04/2013</p>	
	<p>File: SG-BGA-6377Dwg.mcd</p>			<p>Modified:</p>	